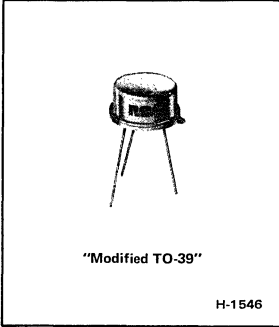




Power Transistors

2N5262



Silicon N-P-N High-Speed Switching Transistor

For Memory-Driver Service in Data-Processing Equipment and Other Critical Industrial Applications

Features:

- Fast switching at 1A:
 $t_{on} = 30 \text{ ns max.}$
 $t_{off} = 60 \text{ ns max.}$
- High voltage ratings
- High power-dissipation ratings
- High dc beta at 1A — 25 min.
- Low saturation voltage at 1 A:
 0.5 V typ.
- Maximum-area-of-operation curves for dc and pulse operation
- Hermetic "low-profile TO-39" package
- Meets MIL-S-19500 specifications

RCA-2N5262[®] is a silicon n-p-n, epitaxial planar transistor with characteristics which make it exceptionally desirable for high-speed, high-voltage, high-current switching applications. In addition, the 2N5262 features very short turn-on and turn-off times and low saturation voltages. It is also controlled for freedom from second breakdown under both forward-bias and reverse-bias conditions, when operated within specified maximum ratings.

specification MIL-S-19500, and is hermetically sealed in a metal "low-profile JEDEC TO-39" package.

RCA-2N5262 is primarily intended for use as a driver for "2-1/2D" coincident-current and word-organized magnetic-memory systems, and in the other critical industrial applications requiring switching of large currents through inductive loads.

The 2N5262 meets the requirements of the basic military

● Formerly RCA Dev. No. TA7238.

Maximum Ratings, Absolute-Maximum Values

* COLLECTOR-TO-BASE VOLTAGE	V_{CBO}	75	V
* COLLECTOR-TO-EMITTER VOLTAGE:			
With base open	V_{CEO}	50	V
With emitter-base shorted	V_{CES}	60	V
* EMITTER-TO-BASE VOLTAGE	V_{EBO}	5	V
COLLECTOR CURRENT:			
* Continuous		2	A
Instantaneous (See Fig.4)		3	A
* TRANSISTOR DISSIPATION:	P_T		
At case temperatures up to 25°C		4	W
At case temperatures above 25°C		Derate linearly 22.8 mW/°C	
At ambient temperatures up to 25°C		0.8	W
At ambient temperatures above 25°C		Derate linearly 4.57 mW/°C	
* TEMPERATURE RANGE:			
Storage and operating (Junction)		-65 to 200	°C
* LEAD TEMPERATURE (During soldering):			
At distance $\geq 1/32$ in. (0.8 mm) from seating plane for 10 s max		265	°C

* In accordance with JEDEC registration data format JS-8/RDF-7.

ELECTRICAL CHARACTERISTICS, At Ambient Temperature (T_A) = 25°C

CHARACTERISTIC	SYMBOL	TEST CONDITIONS					LIMITS		UNITS
		VOLTAGE V dc		CURRENT A dc			2N5262		
		V _{CE}	V _{CB}	I _C	I _E	I _B	MIN.	MAX.	
* Collector Cutoff Current: With emitter-to-base junction shorted	I _{CES}	60					—	10	μA
With emitter open	I _{CBO}		75				—	100	
* Emitter-to-Base Cutoff Current (V _{EB} = 5V)	I _{EBO}						—	100	μA
* Collector-to-Emitter Breakdown Voltage	V(BR)CEO			0.01			50	—	V
* Collector-to-Emitter Saturation Voltage	V _{CE(sat)}			1 ^a		0.1	—	0.8	V
* Base-to-Emitter Saturation Voltage	V _{BE(sat)}			1 ^a		0.1	—	1.4	V
* DC Forward Current Transfer Ratio	h _{FE}	1 1 1		0.1 ^a 0.5 ^a 1 ^b			35 40 25	— — —	
Common-Emitter, Small-Signal, Short-Circuit, Forward Current Transfer Ratio (f = 100 MHz)	h _{fe}	10		0.05			2.5	—	
Common-Base, Open-Circuit Output Capacitance (f = 1 MHz)	C _{ob}		10		0		—	15	pF
* Switching Time: Turn-on (t _d + t _r)	t _{ON}			I _C	I _{B1}	I _{B2}			ns
Turn-off (t _s + t _f)		t _{OFF}			1	0.1	—	—	
				1	0.1	—0.1	—	60	

* In accordance with JEDEC registration data format JS-8/RDF-7.

^a Pulsed: Pulse duration = 300 μs; duty factor ≤ 2%.

^b Pulsed: Pulse duration ≤ 400 μs, duty factor ≤ 0.03.

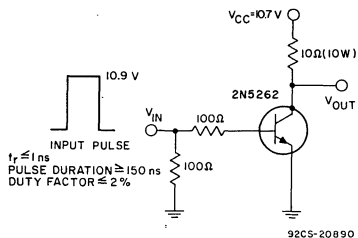


Fig.1—Circuit used to measure turn-on time.

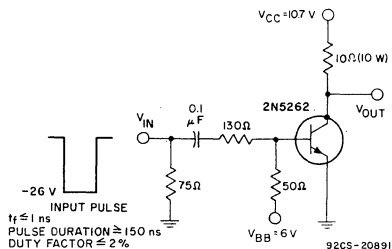


Fig.2—Circuit used to measure turn-off time.

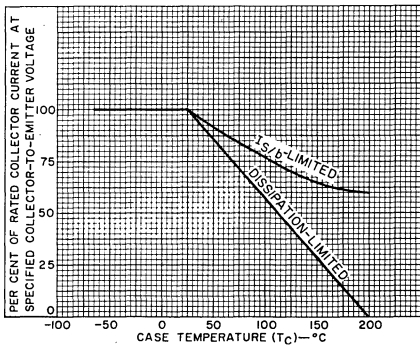


Fig. 3 - Derating curves.

92CS-14868R1

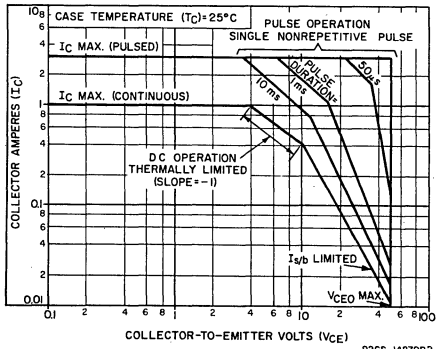


Fig. 4 - Safe area of operation.

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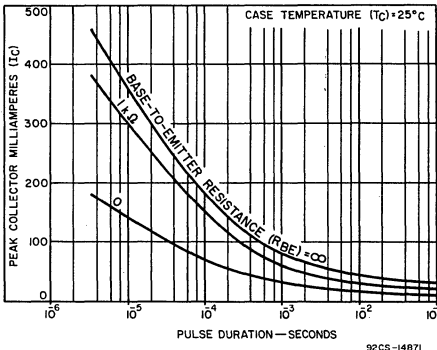


Fig. 5 - Typical second-breakdown characteristics.

92CS-14871

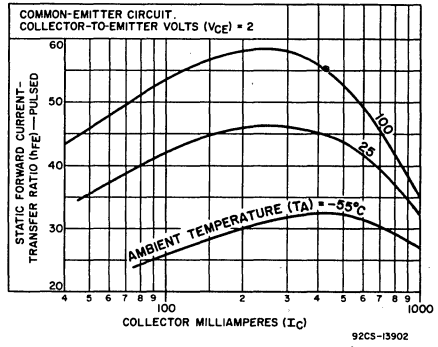


Fig. 6 - Typical dc beta characteristics.

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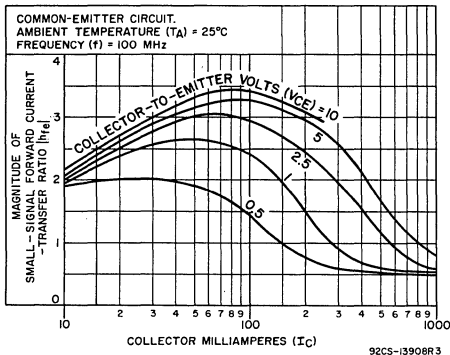


Fig. 7 - Typical small-signal beta characteristics.

92CS-13908R3

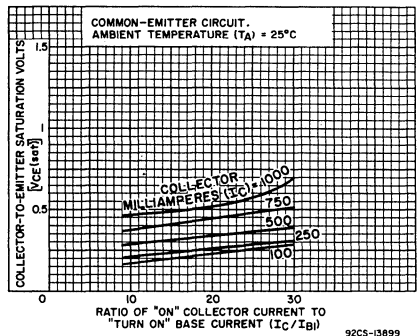


Fig. 8 - Typical saturation-voltage characteristics.

92CS-13899

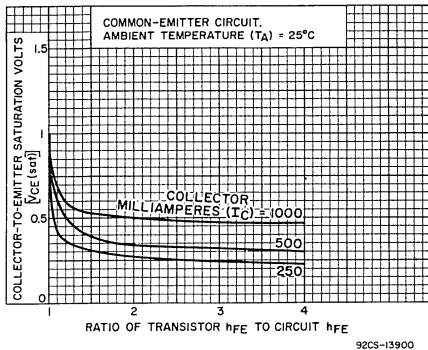


Fig. 9—Typical characteristics of saturation voltage vs. ratio of transistor beta to circuit beta.

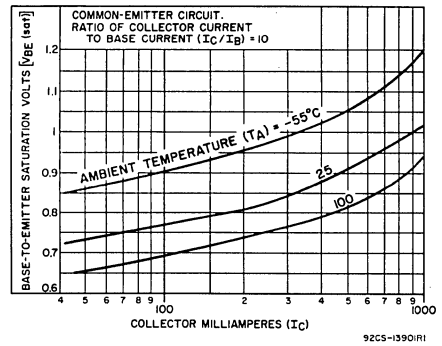


Fig. 10—Typical base-to-emitter saturation voltage vs. collector current.

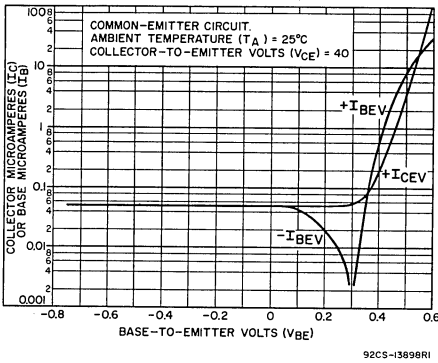


Fig. 11—Typical transfer characteristics.

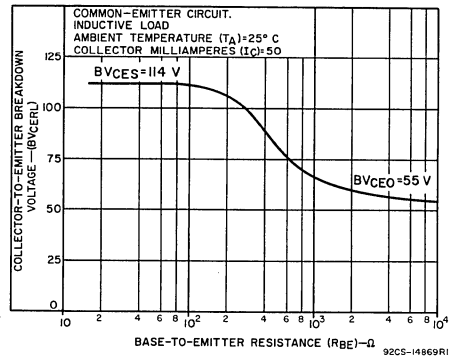


Fig. 12—Typical collector-to-emitter breakdown voltage vs. resistance.

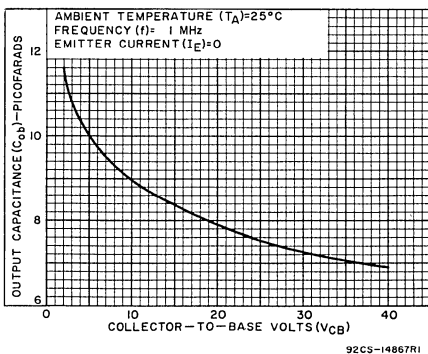


Fig. 13—Typical output capacitance vs. collector-to-base voltage.

TERMINAL CONNECTIONS

- LEAD 1 — EMITTER
- LEAD 2 — BASE
- LEAD 3 — COLLECTOR, CASE

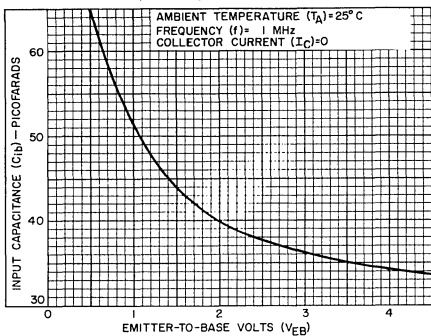


Fig. 14—Typical input capacitance vs. emitter-to-base voltage.

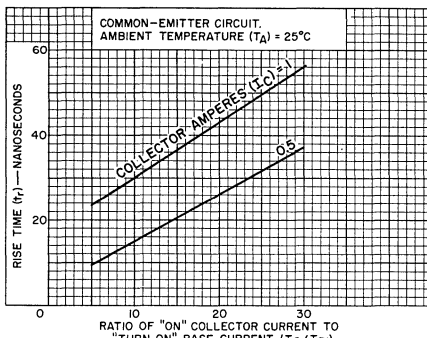


Fig. 15—Typical rise-time characteristics.

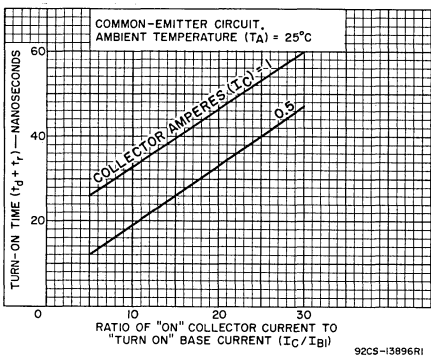


Fig. 16—Typical turn-on time characteristics.

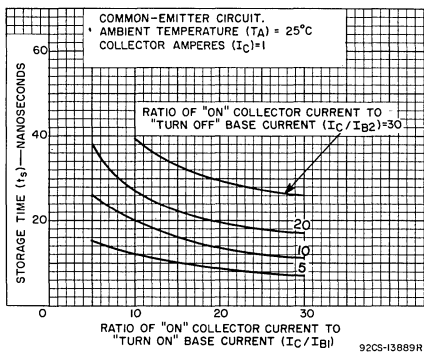


Fig. 17—Typical storage time characteristics.

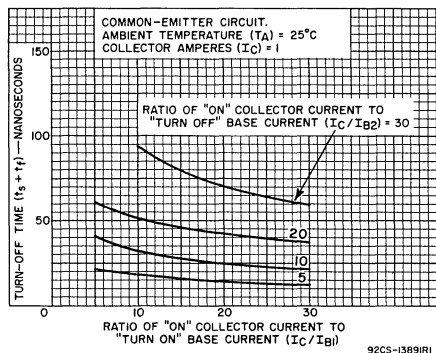


Fig. 18—Typical turn-off time characteristics.

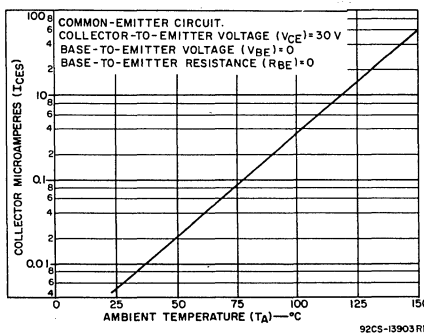


Fig. 19—Typical collector cutoff current as a function of temperature.